



Final Product Change Notification

201906034F01

Issue Date: 21-Jul-2019
Effective Date: 20-Aug-2019



QUALITY

Management Summary

PF0100A and PF0200A C&I product offerings assembly site expansion to NXP ATTJ Tianjin, China for manufacturing flexibility and customer supply assurance.

Change Category

- | | | | | |
|--|---|--|---|---|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input checked="" type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware | <input type="checkbox"/> Other | | | |

PF0100A and PF0200A C&I Product Assembly Site Expansion to NXP ATTJ

Description of Change

NXP Semiconductors announces the Assembly site expansion for the PF0100A and PF0200A Consumer and Industrial family devices associated with this notification, from the current ASEKR, Korea assembly site to the NXP ATTJ Tianjin, China assembly site.

With the assembly site expansion to ATTJ, the opportunity is taken to update the product case outline document 98ASA00405D / SOT684-16:

- Optional view included for ATTJ lead frame Pin 1 identifier chamfered corner shape (current ASEKR Pin 1 identifier is radius circle).
- Update package thickness from 0.9 - 0.8 to 1.0 - 0.8. This is a correction of the package thickness documentation only to reflect current production ASEKR / shipped material. Note there is no physical change, no physical thickness increase to any PF0100A or PF0200A units sourced from ASEKR or ATTJ. Documentation correction only.

Production part numbers remain the same, no new part numbers, for the new NXP ATTJ Tianjin QFN assembled material. See details below in Identification of Affected Products section.

The assembly site expansion was successfully qualified adhering to NXP specifications.

Updated case outline 98ASA00405D Rev D / SOT684-16 is attached, and can be found at: <https://www.nxp.com/docs/en/package-information/SOT684-16.pdf>

Data sheets MMPF0100 and MMPF0200 will be updated to document the case outline revision change.

Please see the attached files for additional details.

Reason for Change

Qualification of NXP ATTJ Tianjin, China assembly site is required for manufacturing flexibility and customer supply assurance.

Identification of Affected Products

Product assembly site, among other information, is reflected in the part marking trace code. The trace code can be used to identify the assembly site for both ASEKR and ATTJ material.

Please refer to the marking comparisons file in the change summary attachment.

No change to orderable part numbers.

Product Availability

Sample Information

Samples are available from 18-Jul-2019

Samples available for:

PF0100A: MMPF0100NPAEP

PF0200A: MMPF0200NPAEP

Production

Planned first shipment 19-Aug-2019

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

PF0100A and PF0200A Consumer and Industrial products will be sourced from both ASEKR and NXP ATTJ assembly sites upon this site expansion PCN 201906034F01 implementation.

Additional information

Self qualification: [view online](#)

Additional documents: [view online](#)

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected

by 20-Aug-2019.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist direct

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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